

EPO-TEK®

World Class LED Adhesives

Heat Sink Attach Electrically & Thermally Conductive

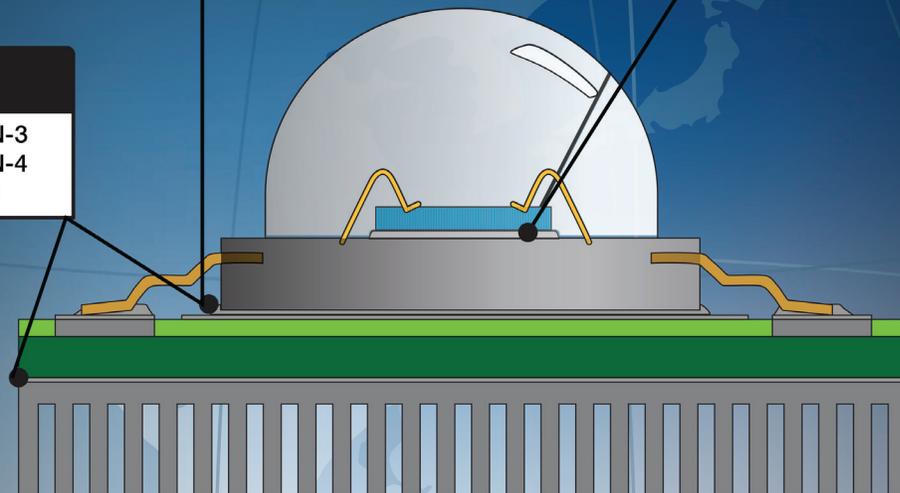
- EK1000
- EK1000-1
- EK1000-1-D
- EK2000
- H20E
- H20E-D

Heat Sink Attach Thermally Conductive

- 930-4
- H70E
- T7109
- T905BN-3
- T905BN-4
- TD1001

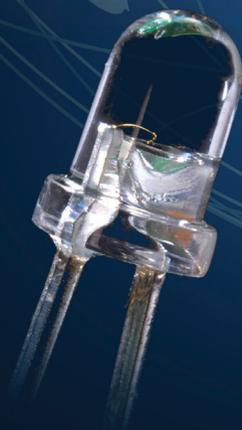
Die Attach Electrically & Thermally Conductive

- EK1000
- EK1000-1
- EK1000-1-D
- EK2000
- H20E
- H20E-D



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- Unsurpassed Thermal and Electrical Management
- Proven Quality and Reliability



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Die Attach



Electrically and Thermally Conductive

EPO-TEK®	Cure Temperature (minimal)	Viscosity @ 23°C (cPs)	Volume Resistivity (ohm-cm)	Thermal Conductivity (W/m ² K)	Performance Features
EK1000 EK2000	200°C - 30 min	1,800 - 3,600 @ 100 rpm	<0.00009	12.6 (150°C/1hr cure) 26.3 (200°C/1hr post-cure)	Adhesive exhibiting exceptional thermal and electrical conductivity. Ideal for high power LEDs.
EK1000-1	200°C - 30 min	13,000 - 21,000 @ 100 rpm	≤0.0007	12.1 (150°C/1hr cure) 22.7 (200°C/1hr post-cure)	Longer dry time than EK1000. Designed for applications requiring longer working time.
EK1000-1-D	200°C - 30 min	2,200 @ 100 rpm	≤0.00008	12.1 (150°C/1hr cure) 22.7 (200°C/1hr post-cure)	Lower viscosity than EK1000. Designed for application requiring longer working time and better flowing.
H20E	150°C - 5 min	2,200 - 3,200 @ 100 rpm	≤0.0004	2.5 (150°C/1hr cure)	Adhesive with proven reliability in low power LEDs.
H20E-D	175°C - 45 sec	1,400 - 1,900 @ 100 rpm	0.0004	3.26 (150°C/1hr cure)	Silver-filled epoxy with a smooth thixotropic consistency. Designed for applications requiring enhanced dispensability.

Heat Sink Attach

Electrically and Thermally Conductive

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Thermally Conductive

930-4	150°C - 10 min 80°C - 6 hours	12,000 - 17,000 @ 20 rpm	≥2 x 10 ¹³	1.7 (150°C/1hr cure)	Adhesive providing excellent heat dissipation and insulating properties.
H70E	175°C - 1 min 80°C - 90 min	4,000 - 7,000 @ 50 rpm	≥1 x 10 ¹³	0.9 (150°C/1hr cure)	Fast curing adhesive recommended for thermal management applications.
T7109	150°C - 10 min 80°C - 8 hours	14,000 - 20,000 @ 20 rpm	≥8 x 10 ¹²	0.7 (40 mil) (150°C/1hr cure) 1.5 (3 mil) (150°C/1hr cure)	Low stress adhesive designed for large bond area die attach and heat sinking applications.
T905BN-3	80°C - 2 hours	2,000 - 7,000 @ 50 rpm	3 x 10 ¹¹	2.0	Adhesive with high thermal conductivity designed for heat sinking and encapsulation.
T905BN-4	80°C - 1 hour 23°C - 1 day	12,000 - 18,000 @ 20 rpm	≥4 x 10 ¹⁴	1.8	Room temperature curing adhesive with pure white color for easy inspection.
TD1001	125°C - 1 hour	10,000 - 22,000 @ 5 rpm	≥2 x 10 ¹³	0.8	White adhesive with low T _g and long pot life for low stress packaging.



Please consult our *Application Experts* at Epoxy Technology to find the most suitable adhesives for specific technical challenges at: techserv@epotek.com.

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